

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





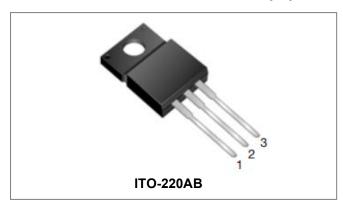








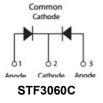
STF3060C(R) SCHOTTKY RECTIFIER

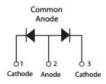


Features

- 150 °C T_J operation
- Ultralow forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Trench MOS Schottky technology
- This is a Pb Free Device
- . All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram





STF3060CR

Applications

- · Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	-	60	V
Average Rectified Forward Current	I _{F (AV)}	50% duty cycle @Tc=100°C, rectangular wave form	15(Per Leg) 30(Per Device)	А
Peak One Cycle Non-Repetitive Surge Current(Per Leg)	I _{FSM}	8.3ms, Half Sine pulse, Tc=25°C	170	Α

Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	TJ	-	-55 to +150	°C
Storage Temperature	T _{stg}	-	-55 to +150	°C
Typical Thermal Resistance Junction to Case(Per Leg)	R _θ JC	DC operation	6	°C/W
Approximate Weight	wt	-	2	g
Case Style	ITO-220AB			

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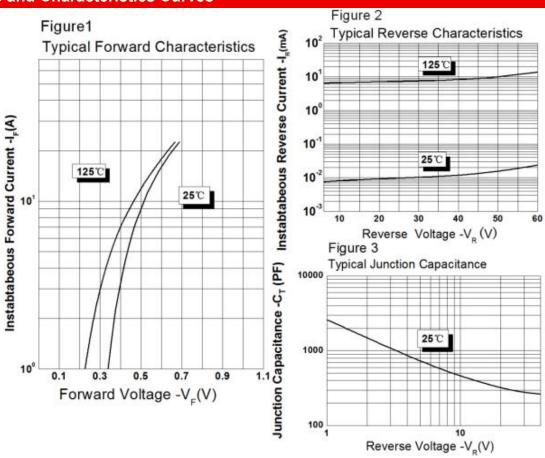


Electrical Characteristics:

Characteristics	Symbol	Condition	Тур.	Max.	Units
Forward Voltage Drop(Per Leg)*	V _{F1}	@ 5A, Pulse, T _J = 25°C	0.42	-	
		@ 7.5A, Pulse, T _J = 25°C	0.48	-	V
		@ 15A, Pulse, T」= 25℃	0.59	0.70	
	V _{F2}	@ 5A, Pulse, T _J = 25°C	0.35	-	
		@ 7.5A, Pulse, T _J =125°C	0.41	-	V
		@ 15A, Pulse, T₁= 125°C	0.55	0.65	
Reverse Current(Per Leg)*	I _{R1}	@V _R = rated V _R , T _J = 25 °C	0.03	1.2	mA
	I _{R2}	@V _R = rated V _R , T _J = 125 ℃	14	45	mA
Junction Capacitance	Ст	$@V_R = 5V, T_C = 25 °C$ $f_{SIG} = 1MHz$	712	-	pF
RSM Isolation Voltage (t = 1.0 second, R. H. < =30%, T _A = 25 °C)		Clip mounting, the epoxy body away from the heatsink edge by more than 0.110" along the lead direction.	-	4500	
	V _{ISO}	Clip mounting, the epoxy body is inside the heatsink.	-	3500	V
		Screw mounting, the epoxy body is inside the heatsink.	-	1500	

^{*} Pulse width < 300 µs, duty cycle < 2%

Ratings and Characteristics Curves



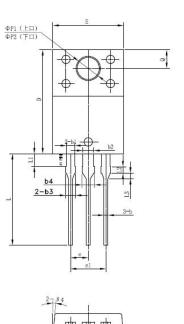
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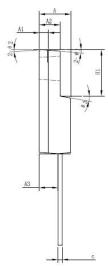






Mechanical Dimensions ITO-220AB





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SYMBOL	Millimeters			
STWIDOL	MIN.	TYP.	MAX.	
Α	4.30	4.50	4.70	
A1	1.10	1.30	1.50	
A2	2.80	3.00	3.20	
A3	2.50	2.70	2.90	
b	0.50	0.60	0.75	
b1	1.10	1.20	1.35	
b2	1.50	1.60	1.75	
b3	1.20	1.30	1.45	
b4	1.60	1.70	1.85	
С	0.50	0.60	0.75	
D	14.80	15.00	15.20	
E	9.96	10.16	10.36	
е		2.55		
e1		5.10		
H1	6.50	6.70	6.90	
L	12.70	13.20	13.70	
L1	1.60	1.80	2.00	
L2	0.80	1.00	1.20	
L3	0.60	0.80	1.00	
ΦΡ1(├ □)	3.30	3.50	3.70	
ΦP2 (下口)	2.99	3.19	3.39	
Q	2.50	2.70	2.90	
Θ1		5°		
Θ2		4°		
Θ3		10°		
Θ4		5°		
Θ5		5°		

Marking Diagram





Where XXXXX is YYWWL

= Device Type = Package type 30 = Forward Current (30A) = Reverse Voltage (60V) 60 = Configuration = SSG C(R) SSG ΥY = Year WW = Week

= Lot Number

Cautions: Molding resin Epoxy resin UL:94V-0

Tube Specification



Ordering Information

Device	Package	Shipping		
STF3060C(R)	ITO-220AB (Pb-Free)	50 pcs/ tube		

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

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